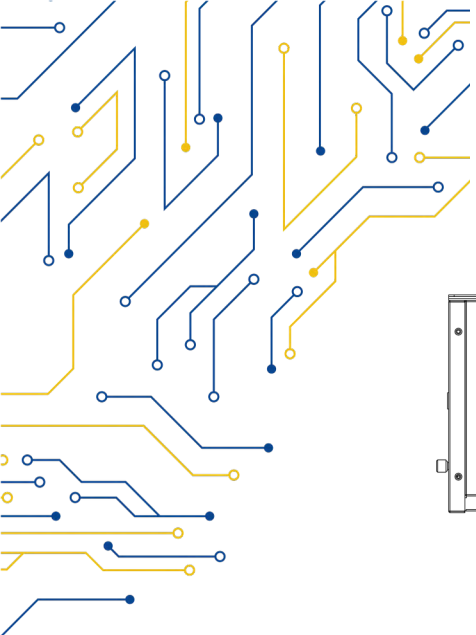




FAN-COOLED INDUSTRIAL BOX PC

MECHANICAL FEATURES	
DIMENSIONS	330 x 196 x 406 mm
CHASSIS	SGCC with forced ventilation
COLOUR	Black
MOUNTING	Desktop
ENVIRONMENTAL FEATURES	
STANDARD CERTIFICATIONS	CE / FCC Class A
OPERATING TEMPERATURE	0°~50°C w/ 0.7m/s airflow
STORAGE TEMPERATURE	-20°~75°C
HUMIDITY	10%~85% Humidity, non-condensing
OTHERS	
WATCHDOG TIMER	From Super I/O to drag RESETCON# 256 Segments, 0, 1, 2, ...255sec
TPM	TPM 2.0 onboard
NOTES	
RAM, CPU and SSD must be specified in the inquiry	

TYPE	FANNED BOX PC
SYSTEM	
CPU	Intel® Core™ 10th Gen (Comet lake-S)
CHIPSET	Intel® Q470E
BIOS	AMI SPI 256Mbit BIOS
RAM	4x 288-pin SO-DIMM DDR4 2933 MHz 128GB (32 GB per DIMM)
GPU	Intel® UHD Graphics Engines (Supports Triple Display)
OPERATING SYSTEM	Windows 10/11, Linux
STORAGE	
SATA/M.2/msATA	1x M.2 (Key M, 2242/2260/2280) with SATA3 and PCIe x4 for SSD 6x SATA3 (6Gb/s)
RAID	Intel® SATA RAID 0/1/5/10
I/O	
USB	4x USB 3.2 Gen2, 2x USB 2.0
SERIAL PORTS	4x RS232, 2x RS232/422/485
VIDEO (TRIPLE DISPLAY)	1x HDMI 2.0a, 1x DP 1.2++, 1x VGA
AUDIO	3x (Mic-In, Line-In, Line-Out), Realtek ALC897/AL887
ETHERNET	1x RJ45 LAN1 Intel® I225LM/I225V with 10/100/1000/2500Mbps 1x RJ45 LAN2 Intel® I219LM with 10/100/1000 Mbps, supports AMT/vPro
GPIO	8x GPI, 8x GPO
PARALLEL	1x Parallel port (shared with GPIO)
EXPANSION SLOTS	
PCIe	3x PCIe Gen3 Slots (PCIe1/PCIe2/PCIe3: single at x16 (PCIe1); dual at x8 (PCIe1) / x8 (PCIe3); triple at x8 (PCIe1) / x4 (PCIe2) / x4 (PCIe3)) 2x PCIe x4 (Gen3)
PCI	2x PCI
M.2	1x M.2 (Key E, 2230) with PCIe x1, USB 2.0 and CNVi for Wireless 1x M.2 (Key B, 3042/3052) with PCIe x1, USB3.2 Gen1, USB 2.0 and SIM for 4G/5G
POWER REQUIREMENTS	
POWER INPUT	110~230V AC



HSB-1711

